

### NCE N-Channel Enhancement Mode Power MOSFET

#### **Description**

The NCE3035G uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

V<sub>DS</sub> =30V,I<sub>D</sub> =35A

 $R_{DS(ON)} < 7.0 \text{m}\Omega$  @  $V_{GS} = 10V$ 

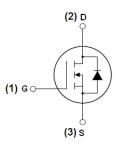
 $R_{DS(ON)} < 12m\Omega$  @  $V_{GS}=4.5V$ 

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

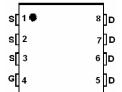
### **Application**

- Secondary side synchronous rectifier
- High side switch in POL DC/DC converter

100% UIS TESTED!



#### Schematic diagram



#### Marking and pin assignment



DFN 5x6 EP top view

#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3035G	NCE3035G	DFN 5x6 EP	-	-	-

### Absolute Maximum Ratings (T<sub>C</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	35	Α
Pulsed Drain Current	I <sub>DM</sub>	120	Α
Maximum Power Dissipation	P <sub>D</sub>	40	W
Derating factor		0.32	W/℃
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	150	mJ
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 150	${\mathbb C}$



# NCE3035G

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 2)	R <sub>eJC</sub>	3.1	°C/W	
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### Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•	•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)				•		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1	1.6	3	V
Drain-Source On-State Resistance	D	V <sub>GS</sub> =10V, I <sub>D</sub> =12A	30	5.9	7.0	mO.
Dialit-Source Off-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	8.9	12.0	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =10V,I <sub>D</sub> =12A	30	-	-	S
Dynamic Characteristics (Note4)				•		
Input Capacitance	C <sub>lss</sub>	\/ -15\/\/ -0\/	-	2330	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =15V, $V_{GS}$ =0V, F=1.0MHz	-	460	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0WID2	-	230	-	PF
Switching Characteristics (Note 4)				•		
Turn-on Delay Time	t <sub>d(on)</sub>		-	18	-	nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =15V,I <sub>D</sub> =12A	-	10	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{GEN}$ =6 $\Omega$	-	34	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Qg	\/ -45\/1 -40A	-	45	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =15V, $I_{D}$ =12A, $V_{GS}$ =10V	-	13	-	nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	10	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =12A	-	0.85	1.2	V
Diode Forward Current (Note 2)	Is		-	-	35	Α
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF = 12A	-	-	47	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3)	-	-	25	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD			y LS+LD)	

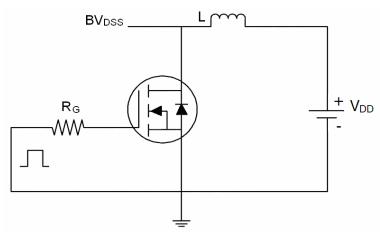
#### Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature}.$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25  $^{\circ}\text{C}$  ,VDD=15V,VG=10V,L=0.1mH,Rg=25 $\Omega$

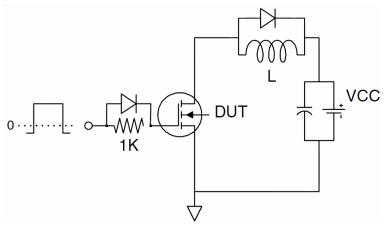


### **Test Circuit**

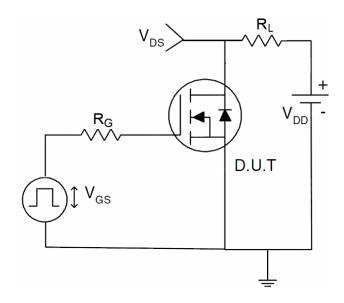
## 1) E<sub>AS</sub> Test Circuits



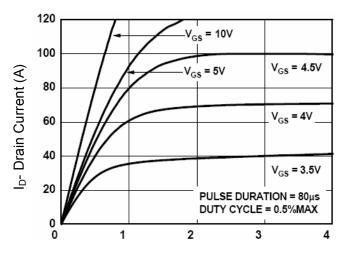
### 2) Gate Charge Test Circuit



### 3) Switch Time Test Circuit

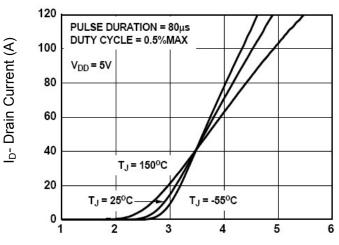


### **Typical Electrical and Thermal Characteristics (Curves)**



Vds Drain-Source Voltage (V)





Vgs Gate-Source Voltage (V) **Figure 2 Transfer Characteristics** 

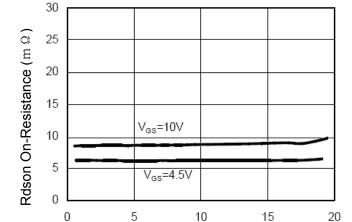
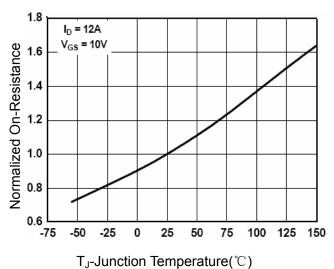


Figure 3 Rdson- Drain Current

I<sub>D</sub>- Drain Current (A)



**Figure 4 Rdson-Junction Temperature** 

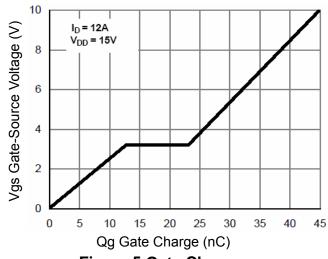
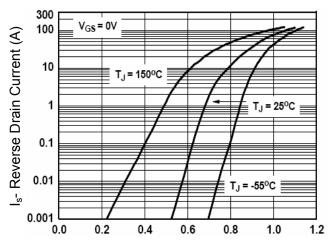


Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward

20

0



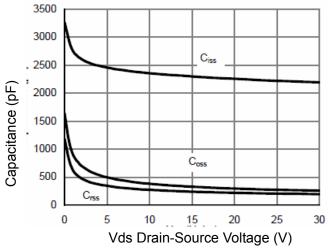
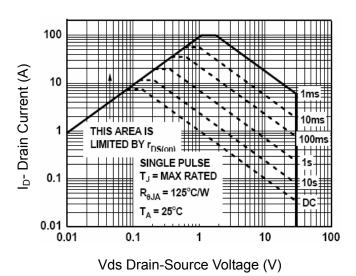
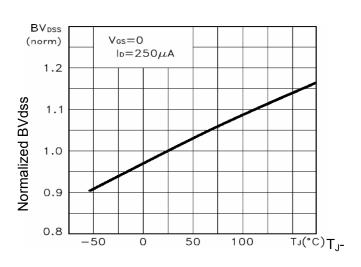


Figure 7 Capacitance vs Vds



**Figure 8 Safe Operation Area** 



Junction Temperature ( $^{\circ}$ C) Figure 9 BV<sub>DSS</sub> vs Junction Temperature

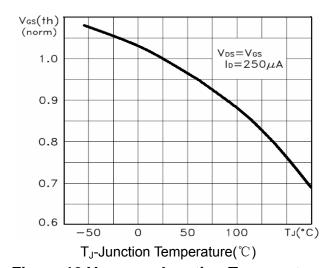
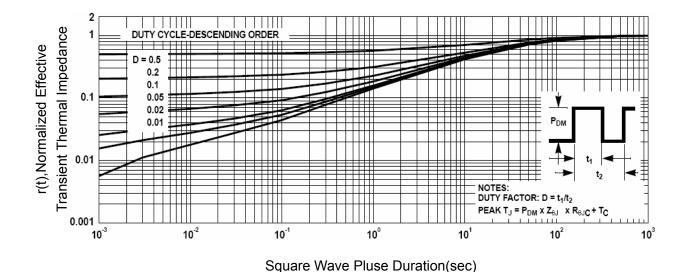
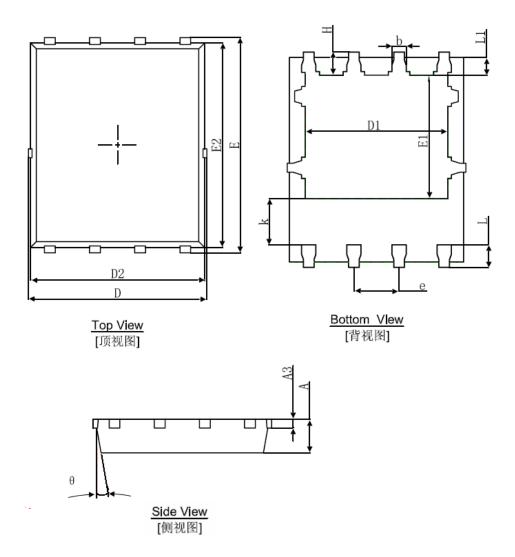


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature



**Figure 11 Normalized Maximum Transient Thermal Impedance** 

## **DFN5X6-8L Package Information**



Symbol Dimensions In		n Millimeters	Dimension	s In Inches	
Symbol	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010	REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.270	TYP.	0.050	TYP.	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	

#### http://www.ncepower.com

**NCE3035G** 

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